### INTEGRATED CIRCUITS

## DATA SHEET

# **74ABT241**Octal buffer/line driver (3-State)

Product specification Supersedes data of 1996 Sep 25 IC23 Data Handbook 1998 Jan 16







#### 74ABT241

#### **FEATURES**

- Octal bus interface
- 3-State buffers
- Power-up 3-State
- Output capability: +64mA/-32mA
- Latch-up protection exceeds 500mA per Jedec Std 17
- ESD protection exceeds 2000 V per MIL STD 883 Method 3015 and 200 V per Machine Model
- Inputs are disabled during 3-State mode

#### **DESCRIPTION**

The 74ABT241 high-performance BiCMOS device combines low static and dynamic power dissipation with high speed and high output drive.

The 74ABT241 device is an octal buffer that is ideal for driving bus lines. The device features two Output Enables ( $1\overline{OE}$ , 2OE), each controlling four of the 3-State outputs.

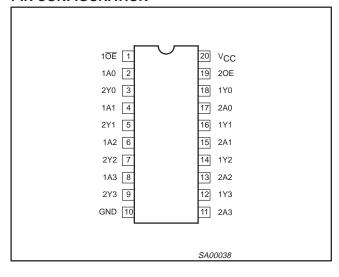
#### **QUICK REFERENCE DATA**

SYMBOL	PARAMETER	CONDITIONS $T_{amb} = 25^{\circ}C; GND = 0V$	TYPICAL	UNIT
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay An to Yn	$C_L = 50pF; V_{CC} = 5V$	2.6 2.7	ns
C <sub>IN</sub>	Input capacitance	$V_I = 0V \text{ or } V_{CC}$	3	pF
C <sub>OUT</sub>	Output capacitance	Outputs disabled; $V_O = 0V$ or $V_{CC}$	7	pF
I <sub>CCZ</sub>	Total supply current	Outputs disabled; V <sub>CC</sub> = 5.5V	50	μΑ

#### **ORDERING INFORMATION**

PACKAGES	TEMPERATURE RANGE	OUTSIDE NORTH AMERICA	NORTH AMERICA	DWG NUMBER
20-Pin Plastic DIP	-40°C to +85°C	74ABT241 N	74ABT241 N	SOT146-1
20-Pin plastic SO	-40°C to +85°C	74ABT241 D	74ABT241 D	SOT163-1
20-Pin Plastic SSOP Type II	-40°C to +85°C	74ABT241 DB	74ABT241 DB	SOT339-1
20-Pin Plastic TSSOP Type I	-40°C to +85°C	74ABT241 PW	74ABT241PW DH	SOT360-1

#### **PIN CONFIGURATION**



#### **PIN DESCRIPTION**

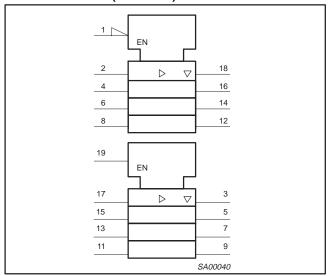
PIN NUMBER	SYMBOL	NAME AND FUNCTION
2, 4, 6, 8	1A0 – 1A3	Data inputs
17, 15, 13, 11	2A0 – 2A3	Data inputs
18, 16, 14, 12	1Y0 – 1Y3	Data outputs
3, 5, 7, 9	2Y0 – 2Y3	Data outputs
1, 19	1 <del>0E</del> , 20E	Output enables
10	GND	Ground (0V)
20	V <sub>CC</sub>	Positive supply voltage

Philips Semiconductors Product specification

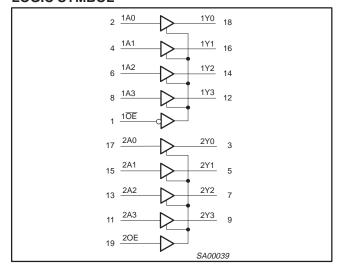
## Octal buffer/line driver (3-State)

74ABT241

#### LOGIC SYMBOL (IEEE/IEC)



#### **LOGIC SYMBOL**



#### **FUNCTION TABLE**

	INP	OUTPUTS			
10E	1An	20E	2An	1Yn	2Yn
L	L	Н	L	L	L
L	Н	Н	Н	Н	Н
Н	Х	L	Х	Z	Z

H = High voltage level

= Low voltage level

X = Don't careZ = High impedance "off" state

#### ABSOLUTE MAXIMUM RATINGS1, 2

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V <sub>CC</sub>	DC supply voltage		-0.5 to +7.0	V
I <sub>IK</sub>	DC input diode current	V <sub>I</sub> < 0	-18	mA
VI	DC input voltage <sup>3</sup>		-1.2 to +7.0	V
I <sub>OK</sub>	DC output diode current	V <sub>O</sub> < 0	-50	mA
V <sub>OUT</sub>	DC output voltage <sup>3</sup>	output in Off or High state	−0.5 to +5.5	V
I <sub>OUT</sub>	DC output current	output in Low state	128	mA
T <sub>stg</sub>	Storage temperature range		-65 to 150	°C

#### NOTES:

- 1. Stresses beyond those listed may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability. The maximum junction temperature of this integrated circuit should not exceed 150°C.

The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

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#### RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	LIM	ITS	UNIT
		Min	Max	
V <sub>CC</sub>	DC supply voltage	4.5	5.5	V
VI	Input voltage	0	V <sub>CC</sub>	V
V <sub>IH</sub>	High-level input voltage	2.0		V
V <sub>IL</sub>	Low-level Input voltage		0.8	V
I <sub>OH</sub>	High-level output current		-32	mA
I <sub>OL</sub>	Low-level output current		64	mA
Δt/Δν	Input transition rise or fall rate	0	5	ns/V
T <sub>amb</sub>	Operating free-air temperature range	-40	+85	°C

#### DC ELECTRICAL CHARACTERISTICS

					LIMITS			
SYMBOL	PARAMETER	TEST CONDITIONS	Tai	<sub>mb</sub> = +25	s∘C		-40°C 85°C	UNIT
			Min	Тур	Max	Min	Max	
V <sub>IK</sub>	Input clamp voltage	$V_{CC} = 4.5V; I_{IK} = -18mA$		-0.9	-1.2		-1.2	V
		$V_{CC} = 4.5V$ ; $I_{OH} = -3mA$ ; $V_I = V_{IL}$ or $V_{IH}$	2.5	2.9		2.5		V
V <sub>OH</sub>	High-level output voltage	$V_{CC} = 5.0V$ ; $I_{OH} = -3mA$ ; $V_I = V_{IL}$ or $V_{IH}$	3.0	3.4		3.0		V
		$V_{CC} = 4.5V$ ; $I_{OH} = -32mA$ ; $V_I = V_{IL}$ or $V_{IH}$	2.0	2.4		2.0		V
V <sub>OL</sub>	Low-level output voltage	$V_{CC} = 4.5V$ ; $I_{OL} = 64mA$ ; $V_I = V_{IL}$ or $V_{IH}$		0.42	0.55		0.55	V
I <sub>I</sub>	Input leakage current	$V_{CC} = 5.5V; V_I = GND \text{ or } 5.5V$		±0.01	±1.0		±1.0	μΑ
I <sub>OFF</sub>	Power-off leakage current	$V_{CC} = 0.0V$ ; $V_I$ or $V_O \le 4.5V$		±5.0	±100		±100	μΑ
I <sub>PU</sub> /I <sub>PD</sub>	Power-up/down 3-State output current <sup>3</sup>	$V_{\underline{CC}}$ = 2.0V; $V_{\underline{O}}$ = 0.5V; $V_{\underline{I}}$ = GND or $V_{\underline{CC}}$ ; $V_{\underline{OE}}$ = $V_{\underline{CC}}$ ; $V_{\underline{OE}}$ = GND		±5.0	±50		±50	μА
I <sub>OZH</sub>	3-State output High current	$V_{CC} = 5.5V; V_O = 2.7V; V_I = V_{IL} \text{ or } V_{IH}$		5.0	50		50	μΑ
I <sub>OZL</sub>	3-State output Low current	$V_{CC} = 5.5V; V_O = 0.5V; V_I = V_{IL} \text{ or } V_{IH}$		-5.0	-50		-50	μΑ
I <sub>CEX</sub>	Output High leakage current	$V_{CC} = 5.5V$ ; $V_O = 5.5V$ ; $V_I = GND$ or $V_{CC}$		5.0	50		50	μΑ
Io	Output current <sup>1</sup>	$V_{CC} = 5.5V; V_{O} = 2.5V$	-50	-100	-180	-50	-180	mA
Іссн		$V_{CC} = 5.5V$ ; Outputs High, $V_I = GND$ or $V_{CC}$		50	250		250	μΑ
I <sub>CCL</sub>	Quiescent supply current	$V_{CC}$ = 5.5V; Outputs Low, $V_I$ = GND or $V_{CC}$		24	30		30	mA
I <sub>CCZ</sub>		$V_{CC}$ = 5.5V; Outputs 3–State; $V_{I}$ = GND or $V_{CC}$		50	250		250	μА
		Outputs enabled, one input at 3.4V, other inputs at $V_{CC}$ or GND; $V_{CC}$ = 5.5V		0.5	1.5		1.5	mA
Δl <sub>CC</sub>	Additional supply current per input pin <sup>2</sup>	Outputs 3-State, one data input at 3.4V, other inputs at $V_{CC}$ or GND; $V_{CC}$ = 5.5V		50	250		250	μА
		Outputs 3-State, one enable input at 3.4V, other inputs at $V_{CC}$ or GND; $V_{CC}$ = 5.5V		0.5	1.5		1.5	mA

#### NOTES:

- 1. Not more than one output should be tested at a time, and the duration of the test should not exceed one second.
- 2. This is the increase in supply current for each input at 3.4V.
- 3. This parameter is valid for any  $V_{CC}$  between 0V and 2.1V with a transition time of up to 10msec. For  $V_{CC}$  = 2.1V to  $V_{CC}$  = 5V  $\pm$  10%, a transition time of up to 100  $\mu$ sec is permitted.

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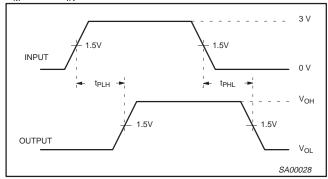
#### **AC CHARACTERISTICS**

GND = 0V;  $t_R$  =  $t_F$  = 2.5ns;  $C_L$  = 50pF,  $R_L$  = 500 $\Omega$ 

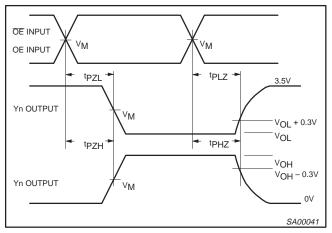
					LIMIT	rs		
SYMBOL	PARAMETER	WAVEFORM	T <sub>a</sub>	<sub>imb</sub> = +25° 'CC = +5.0'	C V	T <sub>amb</sub> = -40° V <sub>CC</sub> = +5	UNIT	
			Min	Тур	Max	Min	Max	
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay An to Yn	1	1.0 1.0	2.6 2.7	4.1 4.2	1.0 1.0	4.6 4.6	ns
t <sub>PZH</sub> t <sub>PZL</sub>	Output enable time to High and Low level	2	1.1 1.3	3.2 4.3	6.3 5.8	1.1 1.3	6.8 6.8	ns
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output disable time from High and Low level	2	1.6 1.0	3.6 2.6	6.1 5.4	1.6 1.0	7.1 5.9	ns

#### **AC WAVEFORMS**

 $V_{M} = 1.5V, V_{IN} = GND \text{ to } 3.0V$ 

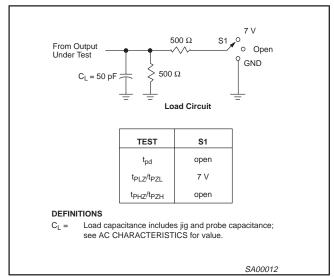


Waveform 1. Waveforms Showing the Input (An) to Output (Yn) Propagation Delays



Waveform 2. Waveforms Showing the 3-State Output Enable and Disable Times

#### **TEST CIRCUIT AND WAVEFORMS**



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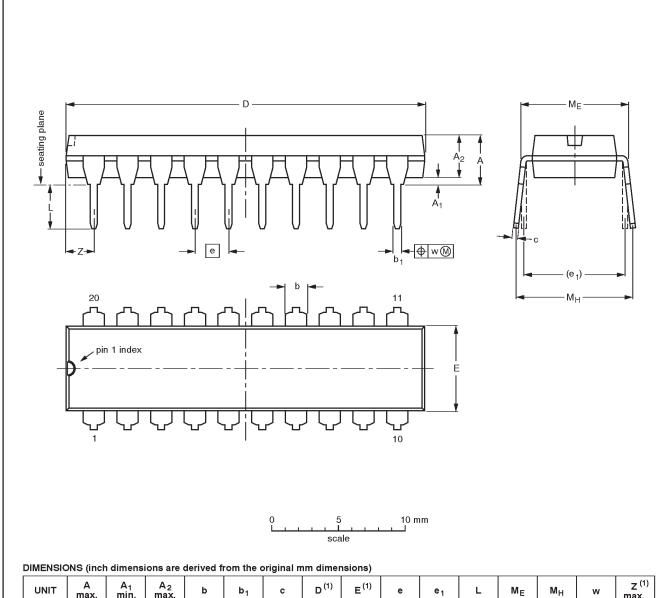
Downloaded from Elcodis.com electronic components distributor

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#### DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	M <sub>E</sub>	M <sub>H</sub>	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

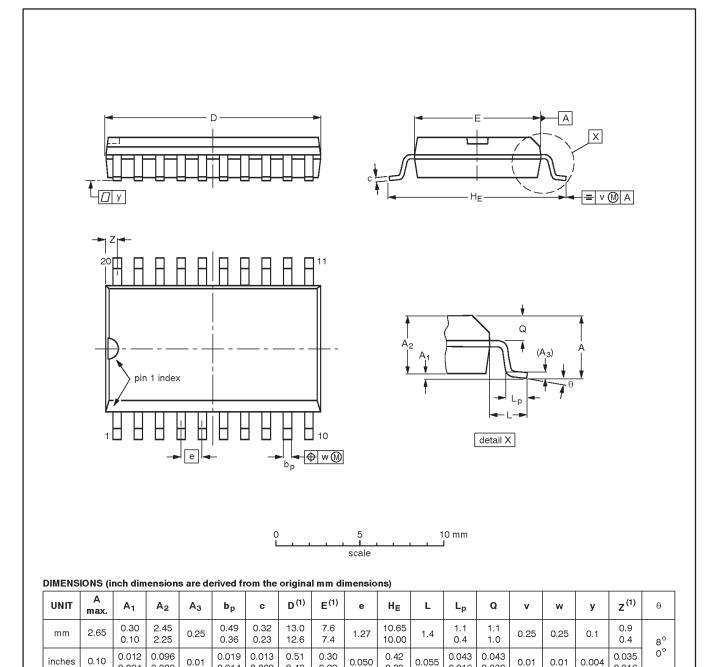
OUTLINE		REFER	RENCES	EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	EIAJ	PROJECTION	ISSUE DATE
SOT146-1			SC603		<del>-92-11-17</del> 95-05-24

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#### 74ABT241

#### SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

0.014

0.009

0.49

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	IEC JEDEC EIAJ			PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				<del>92-11-17</del> 95-01-24	

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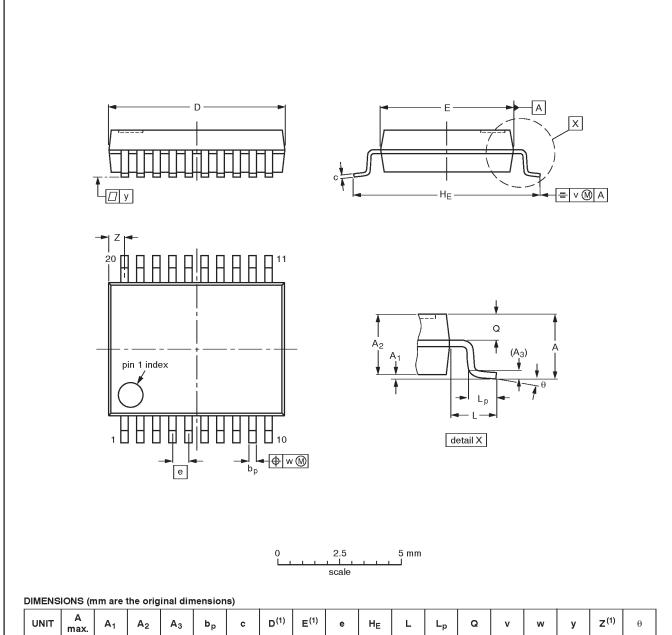
0.004

0.089

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#### SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



UNIT	A max.	Α1	A <sub>2</sub>	A <sub>3</sub>	рb	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

#### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

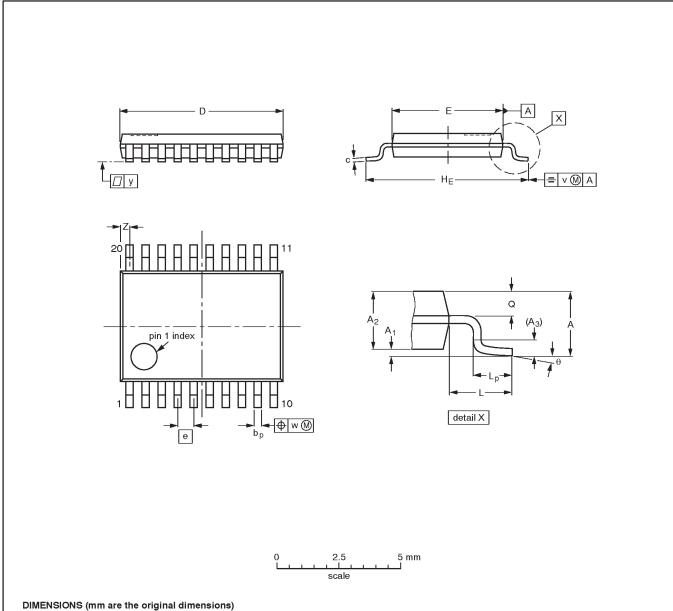
OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE
SOT339-1		MO-150AE				<del>93-09-08</del> 95-02-04

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#### TSSOP20: plastic thin shrink small outline package; 20 leads; body width 4.4 mm

SOT360-1



				,		,												
UNIT	A max.	Α1	A <sub>2</sub>	<b>A</b> <sub>3</sub>	bp	С	D <sup>(1)</sup>	E <sup>(2)</sup>	е	HE	L	Lp	Q	v	w	у	Z <sup>(1)</sup>	θ
mm	1.10	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	6.6 6.4	4.5 4.3	0.65	6.6 6.2	1.0	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.5 0.2	8° 0°

#### Notes

- 1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
- 2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE		
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE
SOT360-1		MO-153AC				<del>93-06-16</del> 95-02-04

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#### Data sheet status

Data sheet status	Product status	Definition [1]
Objective specification	Development	This data sheet contains the design target or goal specifications for product development. Specification may change in any manner without notice.
Preliminary specification	Qualification	This data sheet contains preliminary data, and supplementary data will be published at a later date. Philips Semiconductors reserves the right to make chages at any time without notice in order to improve design and supply the best possible product.
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<sup>[1]</sup> Please consult the most recently issued datasheet before initiating or completing a design.

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